

## Qualified Product Notice

John Lin

Bluetooth Qualification Body (BQB)  
TÜV Rheinland of North America, Inc.

QPN Number: QPN-JLI-051103  
Assessment Date: November 03, 2005  
Listing Date: November 03, 2005  
Applicant: KC Wirefree  
11811 North Tatum Boulevard, Suite  
3031, Pheonix, Arizona 85028 U.S.A  
Contact: Kelly Simonelic  
Product Name: KC21 BT Module  
Product ID: KC21/KC20  
Product Category: Components  
Product Type: Component-SW-Integrated  
Software Version: rev 2.0  
Supported Bluetooth Profiles: GAP, Serial-DevA, Serial-DevB  
Description: Bluetooth Protocol Stack including L2CAP,  
RFCOMM, SDP, GAP, SPP

This listing notice is an essential part of the Bluetooth® qualification program and shows the acceptance of this product as a qualified Bluetooth® product. On the basis of the reviewed submitted compliance folder for the above mentioned product, I certify that the product has passed all requirements to be listed as a pre-qualified Bluetooth® component. The identified Covered Functionality may be considered pre-qualified when used in an End Product in a manner satisfying the conditions described in the Reference Integration Note.

**This Qualified Product Listing Notice is valid only in conjunction with Annex A.**

Pleasanton, 2005-11-03

Place / Date

TÜV Rheinland of North  
America, Inc.  
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Original is signed

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## 1. Reference to Bluetooth Specification

Bluetooth System Specification, version 1.1 from 2001-02-22  
Bluetooth System Specification, version 1.2 from 2003-11-05  
Qualification Program Reference Document, Revision 1.0 with Addendum

Test Case Reference List: release date 2005-05-01

Bluetooth Test Specifications:

Part A: L2CAP Conformance	Version 1.2	2005-01-01
Part D: L2CAP Conformance	Version 0.82	2003-08-01
Part B SDP Conformance	Version 1.2	2004-09-27
Part E: SDP Conformance	Version 0.93	2002-05-06
Part E: SDP Conformance Addendum	Version 0.93a1	2003-10-01
Part F: RFCOMM Conformance	Version 0.93	2003-08-01
Part F: RFCOMM Conformance Addendum	Version 0.93a1	2004-03-01
Part C: GAP Conformance	Version 1.2	2005-05-01
Part K:1 GAP Conformance	Version 0.91	2001-07-02
Part K:1 GAP Conformance Addendum	Version 0.91a1	2003-10-01
Part K:5 SPP Conformance	Version 1.0	2005-05-01

## 2. Covered Functionality Declaration

**Part A: RF** – As defined in part A of the *Bluetooth* core specification version 1.2 including all mandatory features and all optional features.

**Part B: BB** – As defined in part B of the *Bluetooth* core specification version 1.2 including all mandatory features and all optional features except: B.5/6 “Support of AUX1 packet type.

**Part C: LM** – As defined in part C of the *Bluetooth* core specification version 1.2 including all mandatory features and all optional features except: C.2/14 “Broadcast encryption”, C.23/1 “Request page mode to use” and C.23/3 “Request page scan mode to use”. The device was tested and is qualified for the following conditions:

Normal conditions: Room temperature, 3.3V

Low conditions: -25°C, 2.56V

High conditions: +85°C, 3.6V Oscillator: Internal

**Part D: L2CAP** - As defined in the Test Specification Part D: Test Suite Structure (TSS) and Test Purposes (TP) For Logical Link Control and Adaptation Protocol (L2CAP) Specification 1.1, document number 20.B.356/0.81, and L2CAP Addendum to Part D\_0.81, all mandatory and optional features are supported except D.1/4-5, D.2/2, D.3/10-11 and D.4/5-11.

**Part E: SDP** – As defined in the Test Specification Part E: Test Suite Structure (TSS) and Test Purposes (TP) For Service Discovery Protocol (SDP) Specification 1.1, document number 20.B.357/0.93, all mandatory and optional features are supported except E.2/2.

**Part F: RFCOMM with TS07.10** - As defined in the Test Specification Part F:1: Test Suite Structure (TSS) and Test Purposes (TP) For RFCOMM Specification 1.1, document number 20.B.158/0.92, and Addendum to Part F1\_0.92, all mandatory and optional features are supported except F:1.1/18.

**Part H:1** HCI: As defined in Part H:1 of the Bluetooth Specification, Version 1.1.

**Part K:1** GAP: As defined in the Test Specification Part K:1: Test Suite Structure (TSS) and Test Purposes (TP) For Generic Access Profile Specification 1.1, document number 21.B.358/0.91, and Addendum to Part K1\_0.91, all mandatory and optional features are supported.

**Part K:5** SPP: As defined in the Test Specification Part K:5: Test Suite Structure (TSS) and Test Purposes (TP) For Serial Port Profile Specification 1.1, document number 21.B.362/0.92, all mandatory and optional features are supported except K:5.2/2-3, K:5.3/2, K:5.3/6, K:5.4/2, K:5.4/14, K:5.5, K:5.7/2, K:5.7/4, K:5.7/15, K:5.7/19-20, K:5.8/1, K:5.8/4-7, K:5.9/1, K:5.9/5, K:5.9/19, K:5.10/2-3, K:5.10/14, K:5.13/1, K:5.13/3, K:5.13/15 and K:5.13/19

# Annex A to the Qualified Product Listing Notice



## 3. Pre-Qualified Component

Bluetooth ID B01268 RF, BB, LM ZEEVO, Inc. ZV4200 Bluetooth Single Chip Solution, Product ID ZV4301 & ZV4200, HW Version 6.0 A3, SW Version 6.1 & 6.1.1, listed on April 28, 2004 under listing reference number 144 CTCM.

Bluetooth ID B00153 L2CAP, RFCOMM, SDP, GAP, SPP, Widcomm Inc., BTE Bluetooth Communications Software for Embedded Solutions, SW Version 10.05.00, listed on August 11, 2003 under listing reference number BTE-10xx/11xx/12xx.

## 4. Revision History

2005-11-03 First Edition